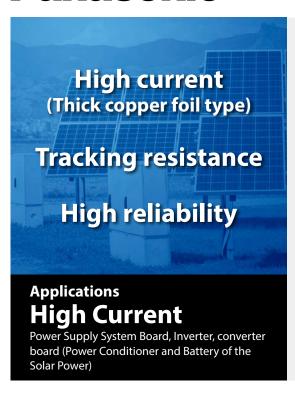
### Panasonic INDUSTRY



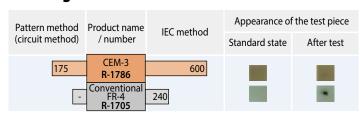
Double-sided copper clad **R-1786** 

# For high current applications Thick copper glass composite circuit board materials

Compatible with high current applications by thick copper foil usage  $(70\mu m)$ .

CEM-3 grade material with high reliability (Tracking resistance CTI ≥600V)

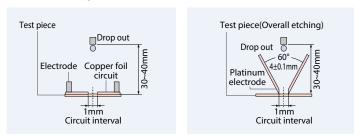
#### **Tracking resistance**



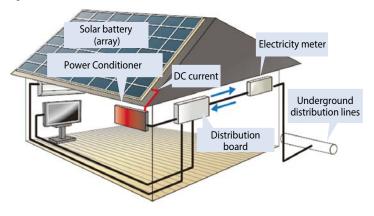
#### **Test method**

Drip 50 drops electrolyte (0.1% aqueous solution of ammonium chloride) towards the central circuit current of 1.0A flows in the voltage of 100V  $\sim$  600V (25V interval).

Measure the voltage current flows for more than 2 seconds.



## General configuration of solar power (personal residence)



Please see our website for Notes before you use.

#### **General properties**

Item		Unit	Unit	R-1786
Tg		Temp. rising rate:10°C/min	°C	140
Solder heat resistance		260°C solder float for 2min	ı	No abnormality
Heat resistance	1oz	A	ı	240°C 60min
CTE x-axis	α1	TMA	ppm/°C	25 (20)
CTE y-axis				28 (23)
CTE z-axis	α1	TMA	ppm/°C	65
Dk	· 1MHz	C-96/20/65	-	4.2
		C-96/20/65+D-24/23		4.2
Df		C-96/20/65		0.011
		C-96/20/65+D-24/23		0.011
Volume resistivity		C-96/20/65	MΩ-m	1×10 <sup>8</sup>
		C-96/20/65+C-96/40/90		5×10 <sup>7</sup>
Surface resistivity		C-96/20/65	МΩ	3×10 <sup>8</sup>
		C-96/20/65+C-96/40/90		1×10 <sup>8</sup>
Insulation resistance		C-96/20/65	МΩ	5×10 <sup>8</sup>
		C-96/20/65+D-2/100		1×10 <sup>7</sup>
Water absorption		E-24/50+D-24/23	%	0.08
Flexural strength	Fill	А	N/mm²	280
Peel strength	2oz	А	kN/m	2.2
		260°C solder float for 20sec		2.1
Alkari resistance		dipping(3min)	-	No abnormality
Flammability		A+E-168/70	-	94V-0

The sample thickness is 1.6mm.

The figure in parentheses is for the thickness of 0.8mm.

<Test method> JIS C6481

The above data are typical values and not guaranteed values.